# 3rd IEEE International Conference on Automation in Manufacturing, **Transportation and Logistics (iCaMaL2023)**

Nov. 3-5, 2023, Wuhan, China

https://stle.whut.edu.cn/iCaMaL2023/abo/



















# <u>Theme: Manufacturing, Transportation and Logistics under the Evolution Trend of Digital Economy</u>

The 2023 IEEE International Conference on Automation in Manufacturing, Transportation and Logistics will be held in Wuhan, a historic center city in China. It will feature plenary speeches, panel sessions, tutorials, workshops, interactive sessions, and invited/special sessions. Contributions are expected from academia, industry, and management agencies. The conference theme is: Manufacturing, Transportation and Logistics under the Evolution Trend of Digital Economy. Technical topics of the conference are focused on advanced automation methods and technologies on Manufacturing, Transportation and Logistics, including but are not limited to:

Intelligent/Advanced manufacturing Automated inspection and quality

control Diagnostics and maintenance Industrial 4.0 system and practice Advanced mechanism and robots MEMS/NEMS/Flexible electronics Energy harvesters/Sensors/Actuators Smart materials and structures Topology & Generative design Mechanical dynamics/Vibration control Smart and digital supply chains Risk management of supply chains Cooperative manufacturing

/logistics/transportation Intermodal/Multimodal transport Physical internet Smart ports/Smart logistics/ITS Sustainable logistics/shipping

Autonomous transportation Logistic networking and super network Port Logistics Port handling and transport process

Novel/Comprehensive transportation Traffic risk assessment and control Container routing/Vehicle routing Scheduling and resource allocation Data driven Scheduling/Decision Coordinated planning/scheduling Service network design

Multi-level multi-objective optimization Simulation based optimization/scheduling Modeling/Simulation/Optimization of complex systems Resilience and fault tolerance

Autonomous agents and multi-agents Decarbonization/Green technology

Formation control/cooperative operation Human-machine interaction

Facility location/Multiple mode positioning Autonomous vehicles/ AGV

Mobile robots/Intelligent robots Remote Driving/Vehicle to everything Sensor design, integration and fusion

Sensor networks

5G application Cooperative sensing/control

Big Data technology/management

Block chain

Cyber-physical systems/IoT Digital Twin/VR/AR/MR/Metaverse Cloud computing/Edge computing

Deep learning Machine vision Artificial intelligence

**Sponsors** 

Wuhan University of Technology; Base for International Science and Technology Cooperation on Smart Shipping and

Maritime Safety; Base of Foreign Outstanding Expertise-Introduction for Disciplines Innovation for Smart Shipping and Maritime Safety; Science Technology on Thermal Energy and Power Laboratory

## Call for Special Sessions/ Workshop

Interested attendees are encouraged to propose special sessions/workshops, each of which consists of five papers providing a focused discussion of new or innovative topics. Each proposal must include the session/workshop title, description, organizers and affiliations. Proposals should be sent to icamal@whut.edu.cn.

#### Web Site and Contact Email for Inquires

Email: icamal@whut.edu.cn;

Special session papers will undergo the same intense review process and submission is not a guarantee for acceptance. Special session papers must be clearly indicated when submitted with a copy sent to the designated special session organizer.

#### Paper Submission & Publication

Complete manuscripts must be electronically submitted through the conference submission website: https://cmt3.research.microsoft.com

Submitted manuscripts should be within six (6) pages in IEEE two-column format, including figures, tables, and references. Please use the templates at http://www.ieee.org/conferences\_events/conferences/publishing/templates.html from the conference website to prepare your paper. All submissions MUST be in PDF format.

Accepted papers will be published by the Proceedings of IEEE according to the presentation and the authors' choice, and would be indexed by EI (Compendex). Authors of selected qualified papers will be invited to submit revised and expanded version of their papers to special issues of international journals (SCI), such as T-ASE, FSMJ, Sensors...

# **Important Dates**

May 30, 2023 June 30, 2023 Full paper submission due June 30, 2023 July 16, 2023 Paper submission due (only for special session)

July 30, 2023 Aug. 15, 2023 Notification of acceptance

Sept. 30, 2023 Camera-ready copy due

Nov. 3-5, 2023 Conference

#### **General Honorary Chairs**

Xinping Yan, Wuhan University of Tech., China

#### **General Chairs**

Mengchu Zhou, New Jersey Institute of Tech., USA

Chaozhong Wu, Wuhan University of Tech., China

#### **Program Chairs**

Wenfeng Li, Wuhan University of Tech., China

Di Zhang, Wuhan University of Tech.,

# **Special Session Chairs**

Qiang Wang, Wuhan University of Tech., China

Agostino M. Mangini, Polytechnic of Bari, Italy

Jianbin Xin, Zhengzhou University,

### **Tutorial/Workshop Chairs**

Haibin Zhu, Nipissing University, Canada

# **Industry Chairs**

Liang Shu, Wenzhou University, China Jingtao Sun, Hitachi, Japan

**Publicity Chairs** Wenjing Guo, Wuhan University of Tech., China

Shijie Li, Wuhan University of Tech., China

#### **Publication Chairs**

Lijun He, Wuhan University of Tech., China

Antonio Guerrieri, National Research Council of Italy

#### **Award Chair**

Weiming Shen, Huazhong University of Science & Technology, China Giancarlo Fortino, University of Calabria, Italy

#### **Finance Chair**

Jie Mei, Wuhan University of Tech., China

#### **Local Arrangement Chairs**

Xiaohua Cao, Wuhan University of Tech., China

#### **Steering Committee**

Andrea D'Ariano, Universit`a degli Studi "RomaTre", Italy Di Zhang, Wuhan University of Tech., China

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